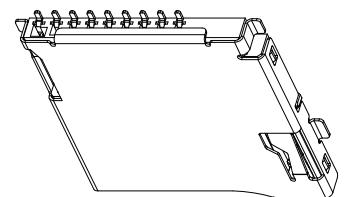


		D	E		
REV.	DESCRIPTION	ECN NO.	NAME	DATE	

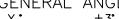
Specification:

1. Electrical Characteristics:
 - Contact Current Rating: 0.5 Amperes.
 - Dielectric Withstanding Voltage: AC 500V r.m.s.
 - Insulation Resistance: 1000 MΩ Minimum.
 - Contact Resistance: 40 mΩ Maximum.
 2. Environmental:
 - Operating Temperature: -25°C ~ +90°C.
 3. Environmental:
 - Mating Cycles: 5,000 Insertions.
 4. Mechanical Characteristics:
 - Card Push Insertion/Out Force: 0.2 ~ 1.40kgf.
 - Contact Separation Force: 0.20kgf Minimum.
 5. Material:
 - Insulator: HI-Temp Plastic UL 94V-0 Rated.
 - Contact: Copper Alloy ($t=0.15\text{mm}$).
 - Shell: Stainless Steel ($t=0.15\text{mm}$).
 - Spring: SWP.



 PAD AREA	Circuit Diagram for Detect Switch	
 KEEP OUT AREA		
WITHOUT CARD	OPEN	 CD GND (normally)
INSERTING CARD	CLOSE	 CD GND (normally)
RECOMMENDED PCB LAYOUT		
GENERAL TOLERANCE ± 0.05		

TF CARD PIN DEFINE			
PIN NO.	NAME	TYPE	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLX	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DATO	I/O/PP	DATE LINE(BIT0)
8	DAT1	I/O/PP	DATE LINE(DIT1)

GENERAL TOLERANCE		DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD					BXCONN®
DIM.	TOL.	TITLE: MICRO SD CARD PUSH PUSH SMT 不鍍金 外焊					
x.	±0.35						
xx	±0.25						
xxx	±0.15						
GENERAL ANGLE:		DWG. NO.: TF-CARD-9P					CHECKED: MAX
x:	±3°						
x.x	±2°						
x.xx		PART NO.: TF-CARD-9P					DRAWN: ELLA
	UNIT: mm	SCALE: none	SHEET: 1 of 1	DWG. SIZE: A4	LAYER: bxconn	APPROVED: WILL	

A	B	C	D		E		
1			REV.	DESCRIPTION	ECN NO.	NAME	DATE
1							
2		NO.1					
3				NO.2			
4							
5		NO.3		NO.4			

GENERAL TOLERANCE	
DIM.	TOL.
x	±0.35
xx	±0.25
xxx	±0.15
GENERAL ANGLE:	
x:	±3°
x,x:	±2°
xxx:	

DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD

BXCONN®

TITLE: MICRO SD CARD PUSH PUSH SMT 不镀金 外焊

DWG. NO.: TF-CARD-9P CHECKED: MAX

PART NO.: TF-CARD-9P DRAWN: ELLA

UNIT: mm SCALE: none SHEET: 1 of 1 DWG. SIZE: A4 LAYER: bxconn APPROVED: WILL

